

PMEG3005ELD

0.5 A low V_F MEGA Schottky barrier rectifier Rev. 1 — 12 April 2011

Product data sheet

Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side

1.2 Features and benefits

Forward current: I_F ≤ 0.5 A

Reverse voltage: V_R ≤ 30 V

Low forward voltage: V_F ≤ 500 mV

AEC-Q101 qualified

Ultra small and leadless SMD plastic package

Solderable side pads

Package height typ. 0.37 mm

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$I_{F(AV)}$	average forward current	square wave; δ = 0.5; f = 20 kHz				
		T _{amb} ≤ 75 °C	<u>[1]</u> _	-	0.5	Α
		T _{sp} ≤ 130 °C	-	-	0.5	Α
I _R	reverse current	V _R = 10 V	-	15	200	μΑ
V_{R}	reverse voltage		-	-	30	V
V_{F}	forward voltage	I _F = 500 mA	[2] _	450	500	mV

^[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm².



^[2] Pulse test: $t_p \le 300 \ \mu s; \ \delta \le 0.02$.

2. Pinning information

Table 2. Pinning

Pin	Description	;	Simplified outline	Graphic symbol
1	cathode	<u>[1]</u>		. 54
2	anode		1 2	1] 2 sym001
			Transparent top view	

^[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
PMEG3005ELD	-	leadless ultra small plastic package; 2 terminals; body 1 \times 0.6 \times 0.4 mm	SOD882D			

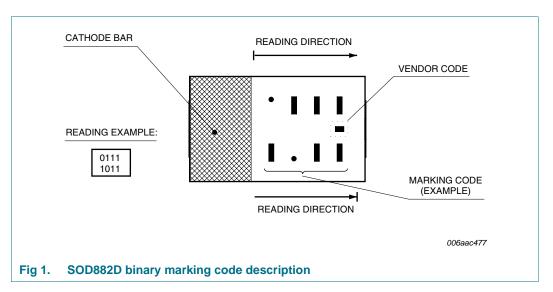
4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
PMEG3005ELD	0011 0000

^[1] For SOD882D binary marking code description, see Figure 1.

4.1 Binary marking code description



PMEG3005ELD

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5. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I _{F(AV)}	average forward current	square wave; $\delta = 0.5$; $f = 20 \text{ kHz}$			
		$T_{amb} \le 75 ^{\circ}C$	<u>[1]</u> -	0.5	А
		T _{sp} ≤ 130 °C	-	0.5	А
I _{FRM}	repetitive peak forward current	$t_p \leq \text{1 ms; } \delta \leq \text{0.25}$	-	1	Α
I _{FSM}	non-repetitive peak forward current	square wave; $t_p = 8 \text{ ms}$	[2] _	3	Α
P _{tot}	total power dissipation	$T_{amb} \le 25 ^{\circ}C$	[3] _	340	mW
			<u>[1]</u> -	660	mW
			<u>[4]</u> _	1000	mW
Tj	junction temperature		-	150	°C
T _{amb}	ambient temperature		-55	+150	°C
T _{stg}	storage temperature		-65	+150	°C

^[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

^[2] $T_i = 25$ °C prior to surge.

^[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

^[4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{\text{th(j-a)}}$	thermal resistance from	in free air	[1][2]	-	-	370	K/W
	junction to ambient		[1][3]	-	-	190	K/W
			[1][4]	-	-	125	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		<u>[5]</u>	-	-	50	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- 2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Soldering point of cathode tab.

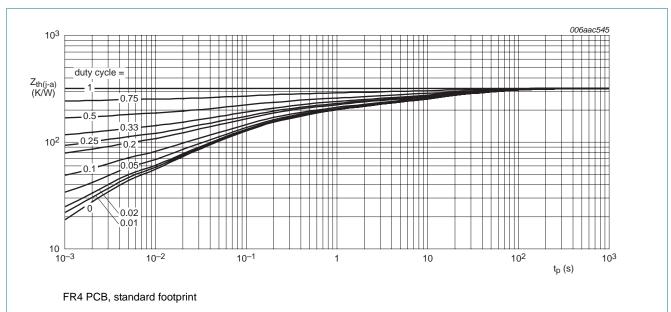
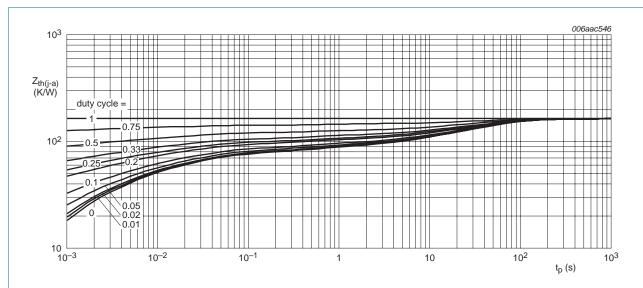
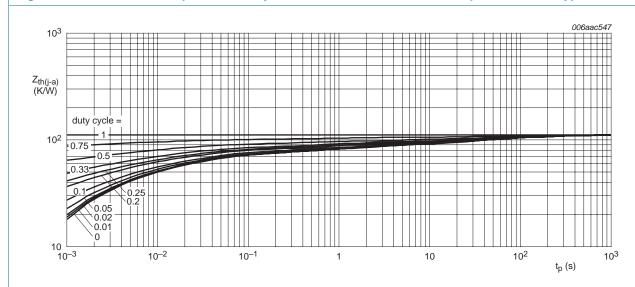


Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

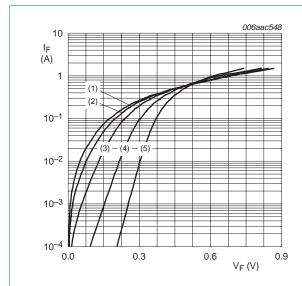
Table 7. Characteristics

 $T_{amb} = 25$ °C unless otherwise specified.

u	-					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{F}	forward voltage		<u>[1]</u>			
		$I_F = 0.1 \text{ mA}$	-	90	180	mV
		$I_F = 1 \text{ mA}$	-	150	200	mV
		$I_F = 10 \text{ mA}$	-	210	270	mV
		I _F = 100 mA	-	300	360	mV
		I _F = 500 mA	-	450	500	mV
I _R	reverse current	V _R = 10 V	-	15	200	μΑ
		V _R = 30 V	-	80	500	μΑ
C _d	diode capacitance	$V_R = 1 V$; $f = 1 MHz$	-	21	30	pF
t _{rr}	reverse recovery time		[2] _	6	-	ns

[1] Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

[2] When switched from I_F = 10 mA to I_R = 10 mA; R_L = 100 Ω ; measured at I_R = 1 mA.





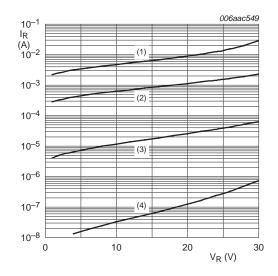
(2)
$$T_i = 125 \,^{\circ}\text{C}$$

(3)
$$T_i = 85 \, ^{\circ}C$$

(4)
$$T_i = 25 \,^{\circ}C$$

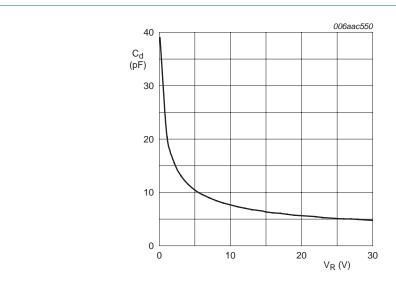
(5) $T_i = -40 \, ^{\circ}C$

Fig 5. Forward current as a function of forward voltage; typical values



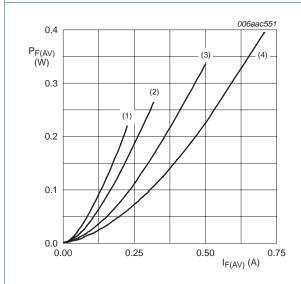
- (1) T_j = 125 °C
- (2) $T_i = 85 \, ^{\circ}C$
- (3) $T_i = 25 \,^{\circ}C$
- (4) $T_i = -40 \, ^{\circ}C$

Fig 6. Reverse current as a function of reverse voltage; typical values



 $f = 1 \text{ MHz}; T_{amb} = 25 \text{ }^{\circ}\text{C}$

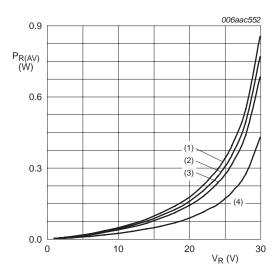
Fig 7. Diode capacitance as a function of reverse voltage; typical values



T_j = 150 °C

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

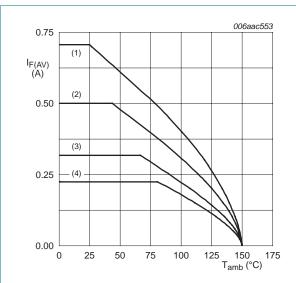
Fig 8. Average forward power dissipation as a function of average forward current; typical values



T_j = 125 °C

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

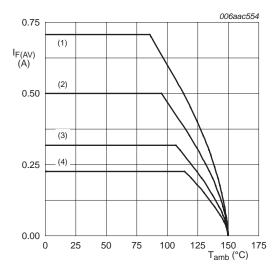
Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; f = 20 kHz
- (3) $\delta = 0.2$; f = 20 kHz
- (4) $\delta = 0.1$; f = 20 kHz

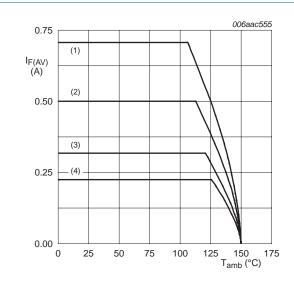
Fig 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; f = 20 kHz
- (3) $\delta = 0.2$; f = 20 kHz
- (4) $\delta = 0.1$; f = 20 kHz

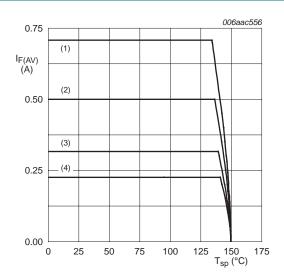
Fig 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; f = 20 kHz
- (3) $\delta = 0.2$; f = 20 kHz
- (4) $\delta = 0.1$; f = 20 kHz

Fig 12. Average forward current as a function of ambient temperature; typical values

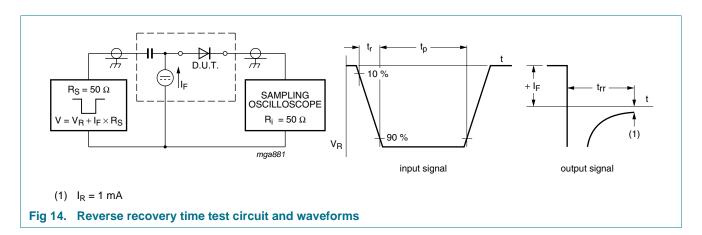


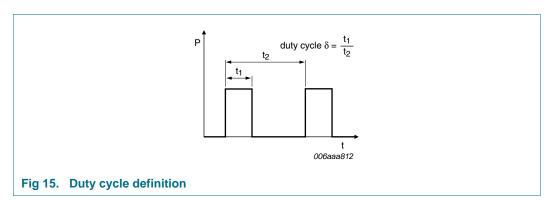
T_i = 150 °C

- (1) $\delta = 1$; DC
- (2) $\delta = 0.5$; f = 20 kHz
- (3) $\delta = 0.2$; f = 20 kHz
- (4) $\delta = 0.1$; f = 20 kHz

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information



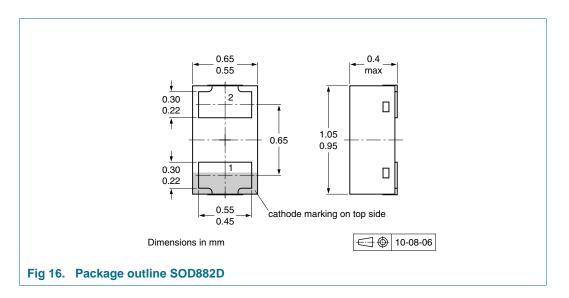


The current ratings for the typical waveforms as shown in Figure 10, 11, 12 and 13 are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

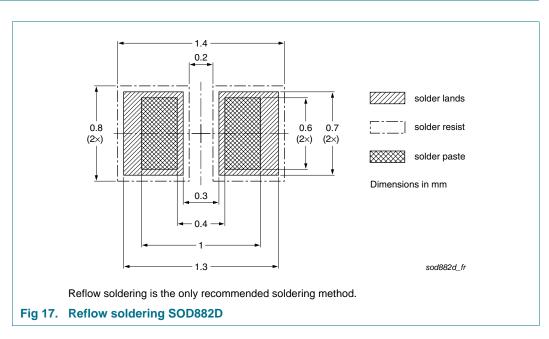
Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity
			10000
PMEG3005ELD	SOD882D	2 mm pitch, 8 mm tape and reel	-315

^[1] For further information and the availability of packing methods, see Section 14.

11. Soldering



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12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3005ELD v.1	20110412	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

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